PCN20008A: Conversion to Cu Wire for SmartFusion, IGLOO2, and SmartFusion2 (Addendum)

September 14, 2020

Description

Microsemi SoC successfully completed the qualification run to convert IGLOO2/SmartFusion2 devices in TQG144 from Au wire to Gold Coated Palladium Copper wire (AuPdCu, also known as AuPCC).

The qualification run for SmartFusion in FG/FGG256 has been postponed and new expected qualification completion is by March 15, 2021.

There is no change in assembly site location. SmartFusion devices in FG/FGG256 will remain at UTAC in Dongguan China. IGLOO2/SmartFusion2 devices in TQG144 assembly support will remain at Amkor Philippines.

Reason for Change

Conversion to AuPdCu (AuPCC) wire is aligned with the current industry trend. Our assembly vendors have extensive experience in copper bond wire assembly. There is no expected impact in product moisture sensitivity level (MSL), product functionality, performance, quality, or reliability.

Products assembled with copper wire only use halogen-free materials.

Application Impact

There is no change in form, fit, function, quality, or reliability of the devices.

Part Numbers Affected

Note: This PCN also affects any special part numbers derived from any part numbers listed in the following table.

SmartFusion	SmartFusion2		IGLOO2	
A2F200M3F-1FG256	M2S005-1TQG144	M2S010-1TQG144	M2GL005-1TQG144	M2GL010-1TQG144
A2F200M3F-1FG256I	M2S005-1TQG144I	M2S010-1TQG144I	M2GL005-1TQG144I	M2GL010-1TQG144I
A2F200M3F-1FGG256	M2S005S-1TQG144	M2S010S-1TQG144	M2GL005S-1TQG144	M2GL010S-1TQG144
A2F200M3F-1FGG256I	M2S005S-1TQG144I	M2S010S-1TQG144I	M2GL005S-1TQG144I	M2GL010S-1TQG144I
A2F200M3F-FG256	M2S005S-TQG144	M2S010S-TQG144	M2GL005S-TQG144	M2GL010S-TQG144
A2F200M3F-FG256I	M2S005S-TQG144I	M2S010S-TQG144I	M2GL005S-TQG144I	M2GL010S-TQG144I
A2F200M3F-FGG256	M2S005-TQG144	M2S010-TQG144	M2GL005-TQG144	M2GL010-TQG144
A2F200M3F-FGG256I	M2S005-TQG144I	M2S010-TQG144I	M2GL005-TQG144I	M2GL010-TQG144I

Production Shipment Schedule

Microsemi is starting to ship IGLOO2/SmartFusion2 in TQG 144 with Cu wire whereas shipment of SmartFusion in FG/FGG256 with Cu wire may begin from April 1, 2021.

Microsemi reserves the right to continue the shipment of devices with Au wire following the change of implementation date.

Customers may receive a mix of pre-conversion products with Au wire and products with AuPdCu (AuPCC) wire interchangeably, following the change of implementation date.

Qualification Data

The qualification report for IGLOO2/SmartFusion2 in TQG144 is available. The qualification report for SmartFusion in FG/FGG256 is expected by March 15, 2021.

Samples Availability

For sample request, please contact your local sales representatives.

Contact Information

If you have any questions about this subject, contact Microsemi Technical Support department by using the support portal at *https://soc.microsemi.com/Portal/Default.aspx*.

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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